

IN THE CLAIMS

1. (cancelled)

2. (currently amended) An apparatus for installing pin connectors to a circuit board, said apparatus comprising:

- a pin array;

- a support surface means defining an engagement area for an application of downward installation force to press fit said pin array to the circuit board, said support surface supporting said pin array during press fit installation to the board; and,

- an enclosure means for receiving said support surface means;

wherein said pin array is at least partially enclosed within said enclosure means.

3. (currently amended) An- The apparatus as in of claim 2 wherein said support surface means further comprises an encapsulation means encapsulant dispensed into said enclosure.

4. (currently amended) An- The apparatus as in of claim 3 wherein said encapsulation means encapsulant further comprises an epoxy-means.

5. (currently amended) An- The apparatus as in of claim 3 wherein said encapsulation means further comprises a transverse support means for said pin array encapsulant is configured to provide transverse support to said pin array during installation to a circuit board.

6. (currently amended) An- The apparatus as in of claim 3 wherein said encapsulation means further comprises an axial support means for said pin array encapsulant is configured to provide axial support to said pin array during installation to a circuit board..

7. (currently amended) An- The apparatus as in of claim 3 wherein said encapsulation means further comprises an encapsulation means for surrounding encapsulant substantially surrounds said pin array.

8. (currently amended) ~~An~~ The apparatus as in of claim 2 further comprising a pin guide, wherein said pin array is at least partially enclosed within said pin guide as well as within said encapsulation means support surface.

9. (currently amended) An apparatus for installing pin connectors comprising:

- a connector-means;
- a pin array extending through said connector;
- a header-means; and
- a support-means surface;

wherein said connector means is matingly engaged with said header-means, thus forming an enclosure for said pin array, and said support surface-means encapsulates said pin array and provides for a downward force to be applied from above a pin the pin array.

10. (currently amended) ~~An~~ The apparatus as in of claim 9 further comprising means for bonding wherein said connector-means and said header means are bonded together.

11. (original) An apparatus as in claim 9 further comprising a pin guide, wherein said pin array is at least partially enclosed within said pin guide as well as within said encapsulation means support surface.

12-21. (cancelled)